CHALMERS
UNIVERSITY OF TECHNOLOGY

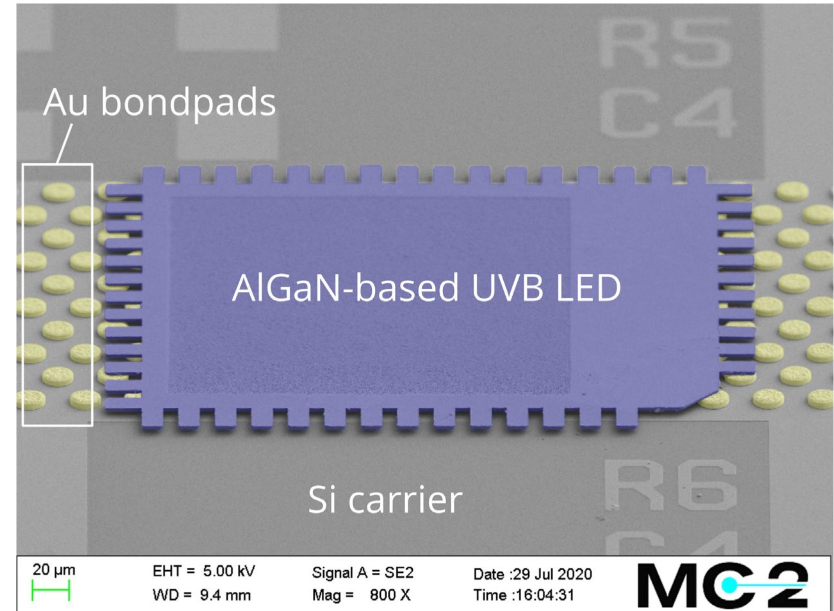
Master thesis proposal

Optimization of electroplated bond pads for flip-chip devices

- Flip-chip integration to realize complex devices: bonding for electrical connection and heat sinking
- Non-planar topography requires adaptable bond pads

Scope: Exploration of eutectic bonding using Au/In, Au/Sn, etc.

- CAD sample design
- Cleanroom fabrication
- Mechanical, electrical and structural characterization



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